

REMARKS

The Examiner objected to the IDS, with respect to the Jablonski & Bielawski reference as it was not in English. Applicant encloses an English abstract thereof for consideration by the Examiner and Form PTO-1449 listing this reference.

The Examiner objected that the application lacked the necessary reference to the prior application. This objection is not understood. See page 1 of the specification at lines 12-15. This statement is slightly amended. Also note that this application was filed under Rule 1.53(b) not 1.60 as stated in the Action. Misspellings are corrected on ages 8, 14 and 15.

The Examiner objected to a typographic error in claim 11; the amended claims contain a correction.

Claims 1-2 and 5 stand rejected as anticipated by US 6,169,330 (Pankove); claims 9-11 stand rejected as anticipated by US 6,271,579 (Going); claims 3, 4, 6-8 and 12 stand rejected as obvious from Pankove with variously US 4,374,391 (Camlibel), 5,629,559 (Miyahara), and 5,502,003 (Ogino). Reconsideration is requested.

Claims 1, 4-7, 9 and 11 are amended. New claims 13-16, 17-20 are added, depending from claims 1, 5, 6 and 9 respectively, and claims 21-24 are added, depending from claims 2, 5, 6 and 9, respectively.

The independent claims 1, 5, 6 and 9 respectively are amended to add a contact comprising an electrically transparent diffusion barrier (ETDB) on the silicon-carbide containing layer. New claims 13-16 recite that the electrically transparent diffusion barrier (ETDB) comprises a transition metal-carbide layer. New claims 17-20 recite that the electrically transparent diffusion barrier (ETDB) comprises an osmium layer. Support for the amendment and added claims 13-20 is found in the specification at page 10, line 15 through page 11, line 9. Claims 21-24 are directed to the flip chip configuration described on page 16 at lines 3-7. Editorial amendments are also made to clarify the claim language.

None of the references cited in the Action disclose or suggest the combination of a silicon-carbide containing layer, substrate or die with a contact comprising an electrically transparent diffusion barrier (ETDB) and an encapsulating or adhesive-encapsulating coating layer as recited in the respective independent claims.

In view of the foregoing amendments and remarks, applicant believes the application should be in condition for allowance. If any questions remain, the Examiner is requested to call the undersigned.

Respectfully submitted,

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